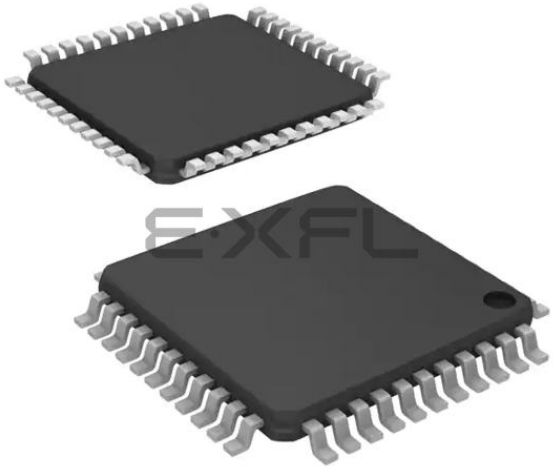


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

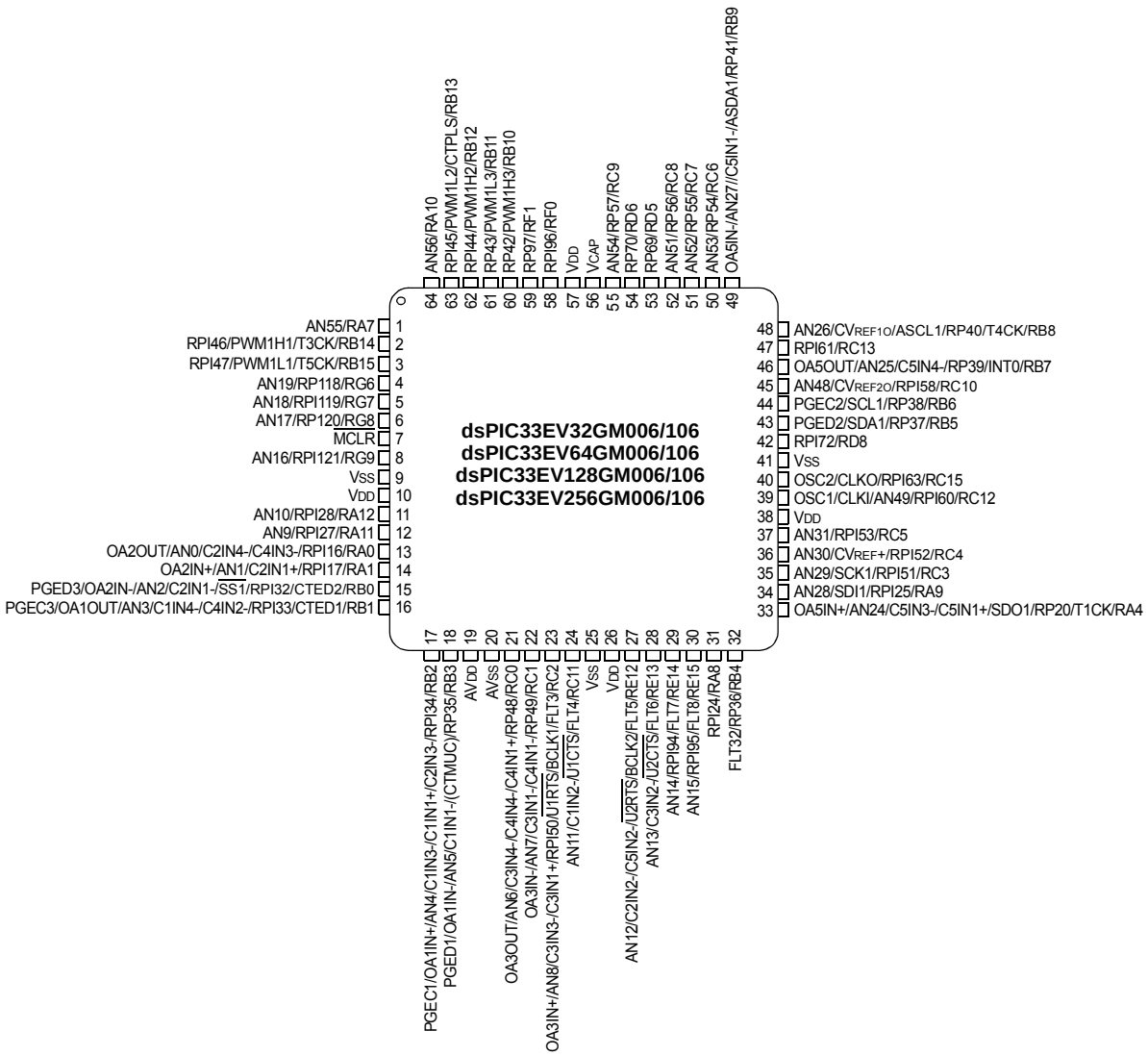
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 24x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev64gm004-i-pt

Pin Diagrams (Continued)

64-Pin TQFP(1,2,3)



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.5 "Peripheral Pin Select (PPS)"** for available peripherals and information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: If the op amp is selected when OPAEN (CMxCON<10>) = 1, the OAx input is used; otherwise, the ANx input is used.

1.0 DEVICE OVERVIEW

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

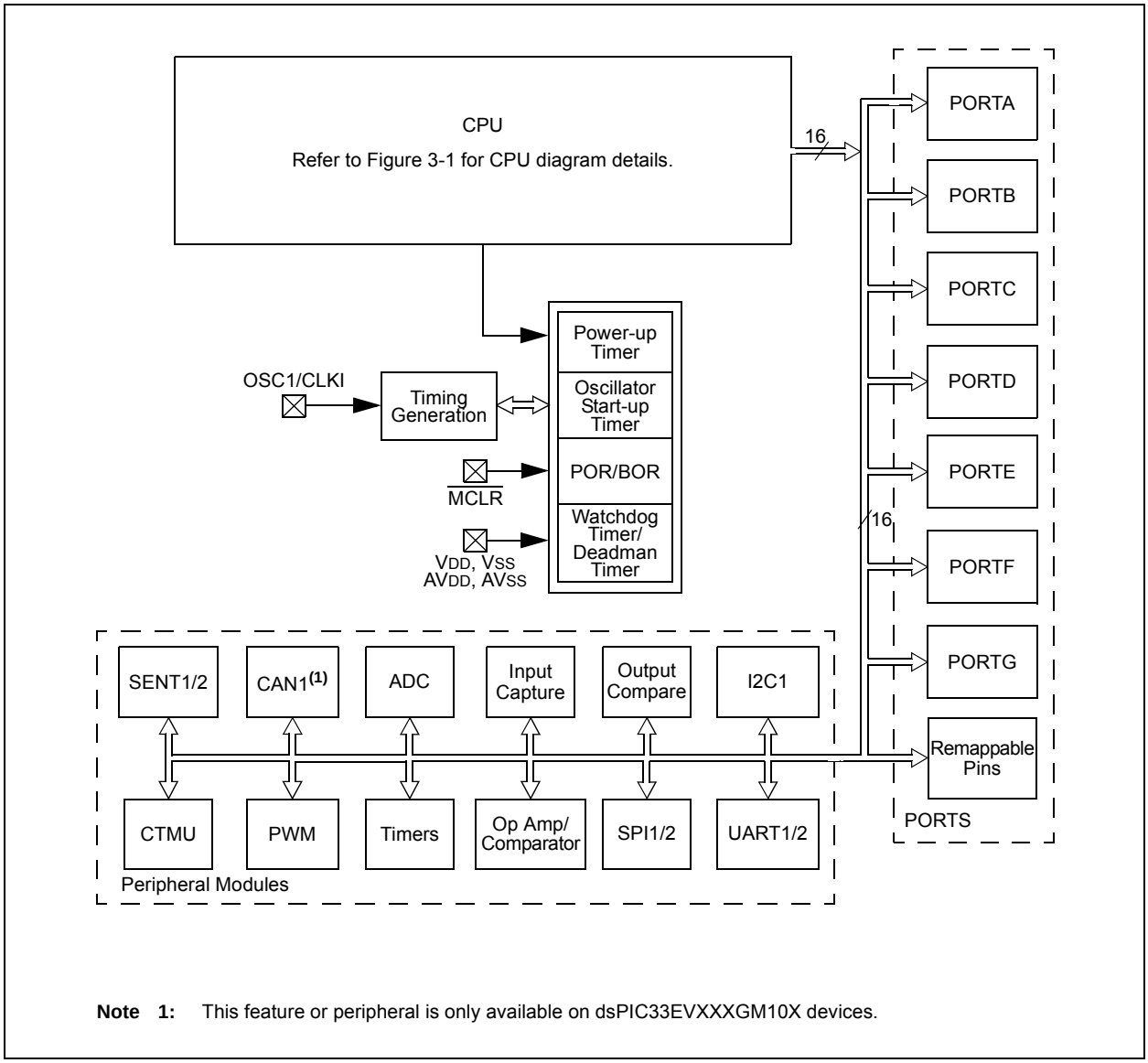
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

This document contains device-specific information for the dsPIC33EVXXXGM00X/10X family Digital Signal Controller (DSC) devices.

dsPIC33EVXXXGM00X/10X family devices contain extensive Digital Signal Processor (DSP) functionality with a high-performance, 16-bit MCU architecture.

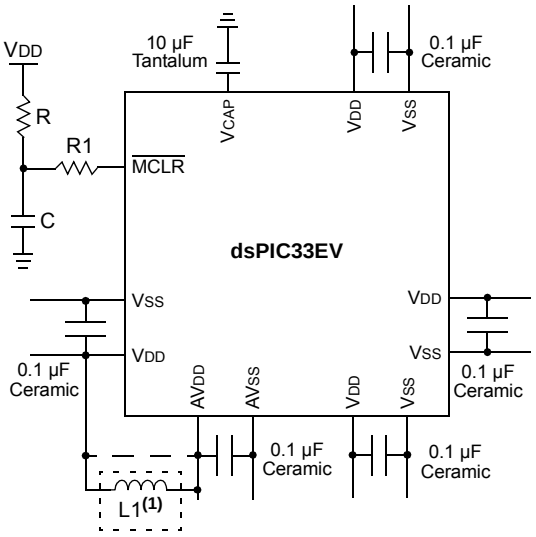
Figure 1-1 shows a general block diagram of the core and peripheral modules. Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

FIGURE 1-1: dsPIC33EVXXXGM00X/10X FAMILY BLOCK DIAGRAM



Note 1: This feature or peripheral is only available on dsPIC33EVXXXGM10X devices.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 1Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{FCNV}{2} \quad \text{(i.e., ADC Conversion Rate/2)}$$

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including DSCs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 µF to 47 µF.

2.3 CPU Logic Filter Capacitor Connection (VCAP)

A low-ESR (<1 Ohms) capacitor is required on the VCAP pin, which is used to stabilize the internal voltage regulator output. The VCAP pin must not be connected to VDD, and must have a capacitor greater than 4.7 µF (10 µF is recommended), with at least a 16V rating connected to the ground. The type can be ceramic or tantalum. See **Section 30.0 "Electrical Characteristics"** for additional information.

The placement of this capacitor should be close to the VCAP pin. It is recommended that the trace length should not exceed one-quarter inch (6 mm).

2.4 Master Clear (MCLR) Pin

The MCLR pin provides two specific device functions:

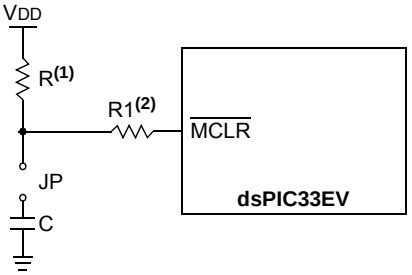
- Device Reset
- Device Programming and Debugging

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-1, it is recommended that the capacitor, C, be isolated from the MCLR pin during programming and debugging operations.

Place the components as shown in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



Note 1: R ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the MCLR pin VIH and VIL specifications are met.

2: R1 ≤ 470Ω will limit any current flow into MCLR from the external capacitor, C, in the event of MCLR pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met.

NOTES:

3.0 CPU

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"CPU"** (DS70359) in the *"dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The CPU has a 16-bit (data) modified Harvard architecture with an enhanced instruction set, including significant support for digital signal processing. The CPU has a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M x 24 bits of user program memory space.

An instruction prefetch mechanism helps maintain throughput and provides predictable execution. Most instructions execute in a single-cycle effective execution rate, with the exception of instructions that change the program flow, the double-word move (`MOV.D`) instruction, PSV accesses and the table instructions. Overhead-free program loop constructs are supported using the `DO` and `REPEAT` instructions, both of which are interruptible at any point.

3.1 Registers

The dsPIC33EVXXXGM00X/10X family devices have sixteen, 16-bit Working registers in the programmer's model. Each of the Working registers can act as a Data, Address or Address Offset register. The sixteenth Working register (W15) operates as a Software Stack Pointer for interrupts and calls.

In addition, the dsPIC33EVXXXGM00X/10X devices include two alternate Working register sets, which consist of W0 through W14. The alternate registers can be made persistent to help reduce the saving and restoring of register content during Interrupt Service Routines (ISRs). The alternate Working registers can be assigned to a specific Interrupt Priority Level (IPL1 through IPL6) by configuring the CTXTx<2:0> bits in the FALTREG Configuration register.

The alternate Working registers can also be accessed manually by using the `CTXTSWP` instruction.

The CCTXI<2:0> and MCTXI<2:0> bits in the CTXTSTAT register can be used to identify the current, and most recent, manually selected Working register sets.

3.2 Instruction Set

The device instruction set has two classes of instructions: the MCU class of instructions and the DSP class of instructions. These two instruction classes are seamlessly integrated into the architecture and execute from a single execution unit. The instruction set includes many addressing modes and was designed for optimum C compiler efficiency.

3.3 Data Space Addressing

The Base Data Space can be addressed as 4K words or 8 Kbytes and is split into two blocks, referred to as X and Y data memory. Each memory block has its own independent Address Generation Unit (AGU). The MCU class of instructions operates solely through the X memory AGU, which accesses the entire memory map as one linear Data Space. On dsPIC33EV devices, certain DSP instructions operate through the X and Y AGUs to support dual operand reads, which splits the data address space into two parts. The X and Y Data Space boundary is device-specific.

The upper 32 Kbytes of the Data Space (DS) memory map can optionally be mapped into Program Space (PS) at any 16K program word boundary. The Program-to-Data Space mapping feature, known as Program Space Visibility (PSV), lets any instruction access Program Space as if it were Data Space. Moreover, the Base Data Space address is used in conjunction with a Data Space Read or Write Page register (DSRPAG or DSWPAG) to form an Extended Data Space (EDS) address. The EDS can be addressed as 8M words or 16 Mbytes. For more information on EDS, PSV and table accesses, refer to **"Data Memory"** (DS70595) and **"dsPIC33E/PIC24E Program Memory"** (DS70000613) in the *"dsPIC33/PIC24 Family Reference Manual"*.

On dsPIC33EV devices, overhead-free circular buffers (Modulo Addressing) are supported in both X and Y address spaces. The Modulo Addressing removes the software boundary checking overhead for DSP algorithms. The X AGU Circular Addressing can be used with any of the MCU class of instructions. The X AGU also supports Bit-Reversed Addressing to greatly simplify input or output data reordering for radix-2 FFT algorithms. Figure 3-1 illustrates the block diagram of the dsPIC33EVXXXGM00X/10X family devices.

3.4 Addressing Modes

The CPU supports these addressing modes:

- Inherent (no operand)
- Relative
- Literal
- Memory Direct
- Register Direct
- Register Indirect

Each instruction is associated with a predefined addressing mode group, depending upon its functional requirements. As many as six addressing modes are supported for each instruction.

REGISTER 5-2: NVMADRU: NONVOLATILE MEMORY UPPER ADDRESS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
NVMADRU<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7-0 **NVMADRU<23:16>:** NVM Memory Upper Write Address bits

Selects the upper 8 bits of the location to program or erase in program Flash memory. This register may be read or written to by the user application.

REGISTER 5-3: NVMADR: NONVOLATILE MEMORY LOWER ADDRESS REGISTER

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
NVMADR<15:8>							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
NVMADR<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **NVMADR<15:0>:** NVM Memory Lower Write Address bits

Selects the lower 16 bits of the location to program or erase in program Flash memory. This register may be read or written to by the user application.

REGISTER 8-14: DMAPPS: DMA PING-PONG STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	PPST3	PPST2	PPST1	PPST0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-4 **Unimplemented:** Read as ‘0’

bit 3 **PPST3:** Channel 3 Ping-Pong Mode Status Flag bit
1 = DMA3STB register is selected
0 = DMA3STA register is selected

bit 2 **PPST2:** Channel 2 Ping-Pong Mode Status Flag bit
1 = DMA2STB register is selected
0 = DMA2STA register is selected

bit 1 **PPST1:** Channel 1 Ping-Pong Mode Status Flag bit
1 = DMA1STB register is selected
0 = DMA1STA register is selected

bit 0 **PPST0:** Channel 0 Ping-Pong mode Status Flag bit
1 = DMA0STB register is selected
0 = DMA0STA register is selected

Table 9-1 provides the Configuration bits which allow users to choose between the various clock modes.

TABLE 9-1: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Oscillator Mode	Oscillator Source	POSCMD<1:0>	FNOSC<2:0>
Fast RC Oscillator with Divide-by-N (FRCDIVN)(1,2)	Internal	xx	111
Fast RC Oscillator with Divide-by-16 (FRCDIV16)(1)	Internal	xx	110
Low-Power RC Oscillator (LPRC)(1)	Internal	xx	101
Primary Oscillator (HS) with PLL (HSPLL)	Primary	10	011
Primary Oscillator (XT) with PLL (XTPLL)	Primary	01	011
Primary Oscillator (EC) with PLL (ECPLL)(1)	Primary	00	011
Primary Oscillator (HS)	Primary	10	010
Primary Oscillator (XT)	Primary	01	010
Primary Oscillator (EC)(1)	Primary	00	010
Fast RC Oscillator (FRC) with Divide-by-N and PLL (FRCPLL)(1)	Internal	xx	001
Fast RC Oscillator (FRC)(1)	Internal	xx	000

Note 1: OSC2 pin function is determined by the OSCIOFNC Configuration bit.

2: This is the default oscillator mode for an unprogrammed (erased) device.

REGISTER 11-4: RPINR7: PERIPHERAL PIN SELECT INPUT REGISTER 7

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IC2R7	IC2R6	IC2R5	IC2R4	IC2R3	IC2R2	IC2R1	IC2R0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IC1R7	IC1R6	IC1R5	IC1R4	IC1R3	IC1R2	IC1R1	IC1R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **IC2R<7:0>:** Assign Input Capture 2 (IC2) to the Corresponding RPn Pin bits
(see Table 11-2 for input pin selection numbers)
10110101 = Input tied to RPI181
•
•
•
00000001 = Input tied to CMP1
00000000 = Input tied to Vss

bit 7-0 **IC1R<7:0>:** Assign Input Capture 1 (IC1) to the Corresponding RPn Pin bits
(see Table 11-2 for input pin selection numbers)
10110101 = Input tied to RPI181
•
•
•
00000001 = Input tied to CMP1
00000000 = Input tied to Vss

REGISTER 17-8: PDCx: PWMx GENERATOR DUTY CYCLE REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PDCx<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PDCx<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **PDCx<15:0>:** PWMx Generator Duty Cycle Value bits

REGISTER 17-9: PHASEx: PWMx PRIMARY PHASE-SHIFT REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PHASEx<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PHASEx<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **PHASEx<15:0>:** PWMx Phase-Shift Value or Independent Time Base Period for the PWM Generator bits

Note 1: If ITB (PWMCONx<9>) = 0, the following applies based on the mode of operation:
Complementary, Redundant and Push-Pull Output modes (PMOD<1:0> (IOCONx<11:10>) = 00, 01 or 10), PHASEx<15:0> = Phase-shift value for PWMxH and PWMxL outputs.

2: If ITB (PWMCONx<9>) = 1, the following applies based on the mode of operation:
Complementary, Redundant and Push-Pull Output modes (PMOD<1:0> (IOCONx<11:10>) = 00, 01 or 10), PHASEx<15:0> = Independent Time Base period value for PWMxH and PWMxL.

REGISTER 17-17: LEBDLYx: PWMx LEADING-EDGE BLANKING DELAY REGISTER

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	LEB<11:8>			
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
LEB<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as '0'

bit 11-0 **LEB<11:0>:** Leading-Edge Blanking Delay for Current-Limit and Fault Inputs bits

REGISTER 22-3: CxVEC: CANx INTERRUPT CODE REGISTER

U-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
—	—	—	FILHIT4	FILHIT3	FILHIT2	FILHIT1	FILHIT0
bit 15							bit 8

U-0	R-1	R-0	R-0	R-0	R-0	R-0	R-0
—	ICODE6	ICODE5	ICODE4	ICODE3	ICODE2	ICODE1	ICODE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **FILHIT<4:0>:** Filter Hit Number bits

10000-11111 = Reserved
01111 = Filter 15
•
•
•
00001 = Filter 1
00000 = Filter 0

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **ICODE<6:0>:** Interrupt Flag Code bits

1000101-1111111 = Reserved
1000100 = FIFO almost full interrupt
1000011 = Receiver overflow interrupt
1000010 = Wake-up interrupt
1000001 = Error interrupt
1000000 = No interrupt
•
•
•
0010000-0111111 = Reserved
0001111 = RB15 buffer interrupt
•
•
•
0001001 = RB9 buffer interrupt
0001000 = RB8 buffer interrupt
0000111 = TRB7 buffer interrupt
0000110 = TRB6 buffer interrupt
0000101 = TRB5 buffer interrupt
0000100 = TRB4 buffer interrupt
0000011 = TRB3 buffer interrupt
0000010 = TRB2 buffer interrupt
0000001 = TRB1 buffer interrupt
0000000 = TRB0 Buffer interrupt

REGISTER 22-4: CxFCTRL: CANx FIFO CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0
DMABS2	DMABS1	DMABS0	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	FSA5	FSA4	FSA3	FSA2	FSA1	FSA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **DMABS<2:0>:** DMA Buffer Size bits
111 = Reserved
110 = 32 buffers in RAM
101 = 24 buffers in RAM
100 = 16 buffers in RAM
011 = 12 buffers in RAM
010 = 8 buffers in RAM
001 = 6 buffers in RAM
000 = 4 buffers in RAM

bit 12-6 **Unimplemented:** Read as '0'

bit 5-0 **FSA<5:0>:** FIFO Area Starts with Buffer bits
11111 = Receive Buffer RB31
11110 = Receive Buffer RB30
•
•
•
00001 = TX/RX Buffer TRB1
00000 = TX/RX Buffer TRB0

24.0 10-BIT/12-BIT ANALOG-TO-DIGITAL CONVERTER (ADC)

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Analog-to-Digital Converter (ADC)"** (DS70621) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Analog-to-Digital (ADC) module in the dsPIC33EVXXXGM00X/10X family devices supports up to 36 analog input channels.

The ADC module can be configured by the user as either a 10-bit, 4 Sample-and-Hold (S&H) ADC (default configuration) or a 12-bit, 1 S&H ADC.

Note: The ADC module needs to be disabled before modifying the AD12B bit.

24.1 Key Features

24.1.1 10-BIT ADC CONFIGURATION

The 10-bit ADC configuration has the following key features:

- Successive Approximation (SAR) Conversion
- Conversion Speeds of up to 1.1 Msps
- Up to 36 Analog Input Pins
- Connections to Four Internal Op Amps
- Connections to the Charge Time Measurement Unit (CTMU) and Temperature Measurement Diode
- Simultaneous Sampling of:
  - Up to four analog input pins
  - Four op amp outputs
- Combinations of Analog Inputs and Op Amp Outputs
- Automatic Channel Scan mode
- Selectable Conversion Trigger Source
- Selectable Buffer Fill modes
- Four Result Alignment Options (signed/unsigned, fractional/integer)
- Operation during CPU Sleep and Idle Modes

24.1.2 12-BIT ADC CONFIGURATION

The 12-bit ADC configuration supports all the features listed previously, with the exception of the following:

- In the 12-bit configuration, conversion speeds of up to 500 ksps are supported
- There is only one S&H amplifier in the 12-bit configuration. Therefore, simultaneous sampling of multiple channels is not supported.

The ADC has up to 36 analog inputs. The analog inputs, AN32 through AN63, are multiplexed, thus providing flexibility in using any of these analog inputs in addition to the analog inputs, AN0 through AN31. Since AN32 through AN63 are multiplexed, do not use two channels simultaneously, since it may result in erroneous output from the module. These analog inputs are shared with op amp inputs and outputs, comparator inputs and external voltage references. When op amp/comparator functionality is enabled, the analog input that shares that pin is no longer available. The actual number of analog input pins and op amps depends on the specific device.

A block diagram of the ADC module with connection options is shown in Figure 24-1. Figure 24-2 shows a block diagram of the ADC conversion clock period.

TABLE 27-1: CONFIGURATION WORD REGISTER MAP

File Name	Address	Device Memory Size (Kbytes)	Bits 23-16	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
FSEC	005780	32	—	AIVTDIS	—	—	—	CSS2	CSS1	CSS0	CWRP	GSS1	GSS0	GWRP	—	BSEN	BSS1	BSS0	BWRP
	00AB80	64																	
	015780	128																	
	02AB80	256																	
FBSLIM	005790	32	—	—	—	—	BSLIM<12:0>												
	00AB90	64																	
	015790	128																	
	02AB90	256																	
Reserved	005794	32	—	Reserved(1)	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
	00AB94	64																	
	015794	128																	
	02AB94	256																	
FOSCSEL	005798	32	—	—	—	—	—	—	—	—	—	$\overline{\text{IESO}}$	—	—	—	—	FNOSC2	FNOSC1	FNOSC0
	00AB98	64																	
	015798	128																	
	02AB98	256																	
FOSC	00579C	32	—	—	—	—	—	—	—	—	PLLKEN	FCKSM1	FCKSM0	IOL1WAY	—	—	OSCIOFNC	POSCMD1	POSCMD0
	00AB9C	64																	
	01579C	128																	
	02AB9C	256																	
FWDT	0057A0	32	—	—	—	—	—	—	—	WDTWIN1	WDTWIN0	WINDIS	FWDTEN1	FWDTEN0	WDTPRE	WDTPS3	WDTPS2	WDTPS1	WDTPS0
	00ABA0	64																	
	0157A0	128																	
	02ABA0	256																	
FPOR	0057A4	32	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	BOREN
	00ABA4	64																	
	0157A4	128																	
	02ABA4	256																	
FICD	0057A8	32	—	—	—	—	—	—	—	—	—	Reserved(2)	—	—	—	—	—	ICS1	ICS0
	00ABA8	64																	
	0157A8	128																	
	02ABA8	256																	

Legend: — = unimplemented, read as '1'.
Note 1: This bit is reserved and must be programmed as '0'.
2: This bit is reserved and must be programmed as '1'.

FIGURE 30-24: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING CHARACTERISTICS

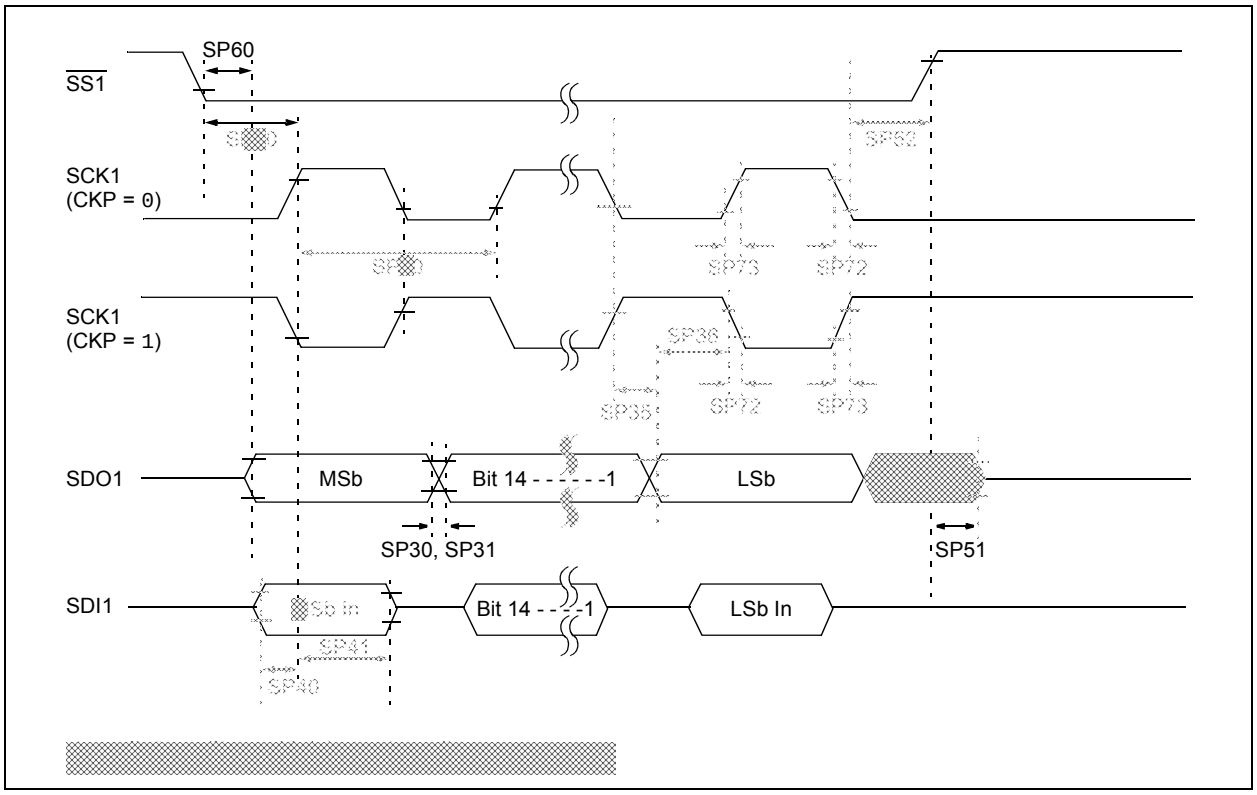


TABLE 30-54: ADC MODULE SPECIFICATIONS

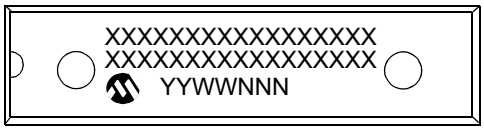
AC CHARACTERISTICS			Standard Operating Conditions (see Note 1): 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
Device Supply							
AD01	AVDD	Module VDD Supply	Greater of: VDD – 0.3 or VBOR	—	Lesser of: VDD + 0.3 or 5.5	V	
AD02	AVSS	Module VSS Supply	VSS – 0.3	—	VSS + 0.3	V	
Reference Inputs							
AD05	VREFH	Reference Voltage High	4.5	—	5.5	V	VREFH = AVDD, VREFL = AVSS = 0
AD06	VREFL	Reference Voltage Low	AVSS	—	AVDD – VBORMIN	V	See **Note 1**
AD06a			0	—	0	V	VREFH = AVDD, VREFL = AVSS = 0
AD07	VREF	Absolute Reference Voltage	4.5	—	5.5	V	VREF = VREFH – VREFL
AD08	IREF	Current Drain	— —	— —	10 600	μA μA	ADC off ADC on
AD09	IAD	Operating Current	— —	5 2	— —	mA mA	ADC operating in 10-bit mode (see **Note 1**) ADC operating in 12-bit mode (see **Note 1**)
Analog Input							
AD12	VINH	Input Voltage Range VINH	VINL	—	VREFH	V	This voltage reflects Sample-and-Hold Channels 0, 1, 2 and 3 (CH0-CH3), positive input
AD13	VINL	Input Voltage Range VINL	VREFL	—	AVSS + 1V	V	This voltage reflects Sample-and-Hold Channels 0, 1, 2 and 3 (CH0-CH3), negative input
AD17	RIN	Recommended Impedance of Analog Voltage Source	—	—	200	Ω	Impedance to achieve maximum performance of ADC

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but is not characterized. Analog modules: ADC, op amp/comparator and comparator voltage reference, will have degraded performance. Refer to Parameter BO10 in Table 30-12 for the minimum and maximum BOR values.

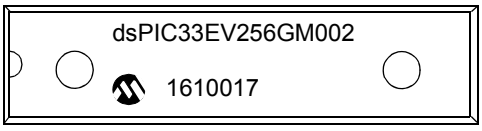
34.0 PACKAGING INFORMATION

34.1 Package Marking Information

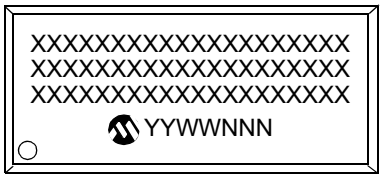
28-Lead SPDIP (.300”)



Example



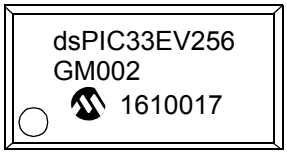
28-Lead SOIC (.300”)



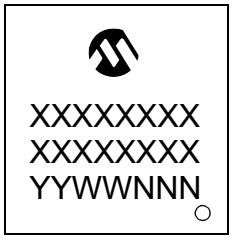
Example

28-Lead SSOP

Example



28-Lead QFN-S (6x6x0.9 mm)



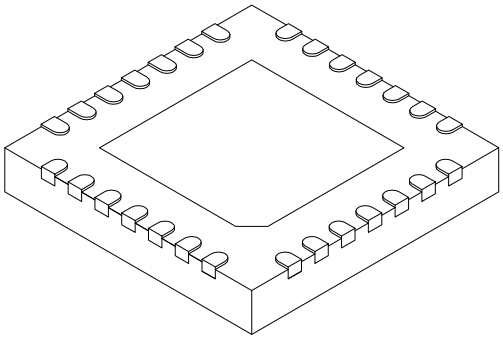
Example

Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

28-Lead Plastic Quad Flat, No Lead Package (MM) - 6x6x0.9mm Body [QFN-S]
With 0.40 mm Terminal Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	3.65	3.70	4.70
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	3.65	3.70	4.70
Terminal Width	b	0.23	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-124C Sheet 2 of 2

THE MICROCHIP WEB SITE

Microchip provides online support via our WWW site at www.microchip.com. This web site is used as a means to make files and information easily available to customers. Accessible by using your favorite Internet browser, the web site contains the following information:

- **Product Support** – Data sheets and errata, application notes and sample programs, design resources, user's guides and hardware support documents, latest software releases and archived software
- **General Technical Support** – Frequently Asked Questions (FAQ), technical support requests, online discussion groups, Microchip consultant program member listing
- **Business of Microchip** – Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

CUSTOMER CHANGE NOTIFICATION SERVICE

Microchip's customer notification service helps keep customers current on Microchip products. Subscribers will receive e-mail notification whenever there are changes, updates, revisions or errata related to a specified product family or development tool of interest.

To register, access the Microchip web site at www.microchip.com. Under "Support", click on "Customer Change Notification" and follow the registration instructions.

CUSTOMER SUPPORT

Users of Microchip products can receive assistance through several channels:

- Distributor or Representative
- Local Sales Office
- Field Application Engineer (FAE)
- Technical Support

Customers should contact their distributor, representative or Field Application Engineer (FAE) for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in the back of this document.

Technical support is available through the web site at: http://microchip.com/support